

#### **Voltage Detector IC Series**

# Standard CMOS Voltage Detector IC

## Pb RoHS

#### BD48xxx series BD49xxx series

#### General Description

ROHM's BD4 8xxx and B D49xxx seri es are hig hly accurate, low current consumption reset IC series. The line up includes BD48xxx devices with N channel open drain output and BD49xxx devices with C MOS output. The devices are available for specific detection voltages ranging from 2.3V to 6.0V in increments of 0.1V.

#### Features

- High accuracy detection
- Ultra-low current consumption
- Two output types (Nch open drain and CMOS output)
- Wide Operating temperature range
- Very small and low height package
- Package SSOP5 is similar to SOT-23-5 (JEDEC)
- Package SSOP3 is similar to SOT-23-3 (JEDEC)

#### Key Specifications

■ Detectio n voltage: 2.3V to 6.0V (Typ.),

0.1V steps

■ High accuracy detection voltage: ± 1.0%
 ■ Ultra-low current consumption: 0 .9µA (Typ.)

■ Operating temperature range: -40°C to +105°C

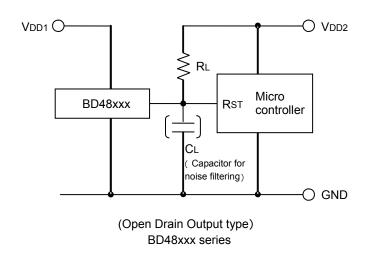
#### ●Package

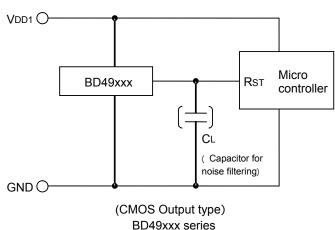
SSOP5: 2.90mm x 2.80mm x 1.15mm SSOP3: 2.90mm x 2.80mm x 1.15mm VSOF5: 1.60 mm x 1.60mm x 0.60mm

#### Applications

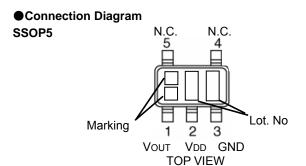
Circuits usin g microcontroll ers or logic circuit s that require a reset.

#### ● Typical Application Circuit

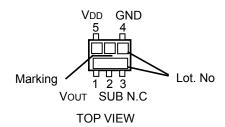




OProduct structure: Silicon monolithic integrated circuit OThis product is not designed protection against radioactive rays.



#### VSOF5



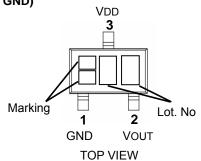
#### Pin Descriptions

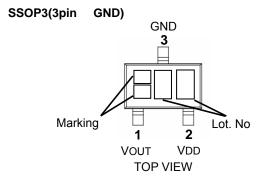
SS	OP5		
	PIN No.	Symbol	Function
	1 V	оит Res	et Output
	2 V	DD <b>Po</b>	wer Supply Voltage
	3 GNI	)	GND
	4 N.C	•	Unconnected Terminal
	5 N.C		Unconnected Terminal

	VSOF5							
PIN No.	Symbol	Function						
1	Vout Res	et Output						
2	SUB	Substrate*						
3 N.C		Unconnected Terminal						
4	GND	GND						
5	VDD Po	wer Supply Voltage						

<sup>\*</sup>Connect the substrate to GND.

#### SSOP3(1pin GND)





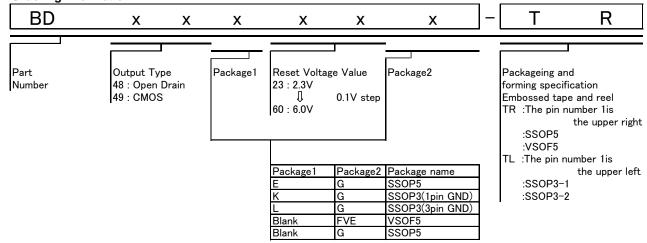
#### ●Pin Descriptions

SS	OP3-1		
	PIN No.	Symbol	Function
	1	GND	GND
	2	Vout Res	et Output
	3	Vdd	Power Supply Voltage

	SSOP3-2							
PIN No.	Symbol	Function						
1	Vout Res	et Output						
2	VDD Po	wer Supply Voltage						
3	GND	GND						

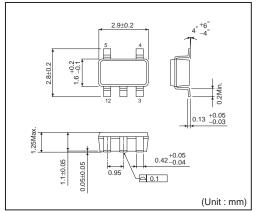
#### Ordering Information

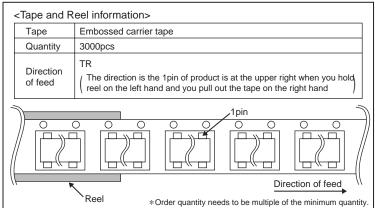
note)



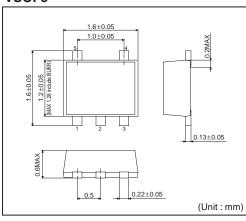
Please be new and, in hope of SSOP5, choose the package 1 by "E" and package 2" G."

#### SSOP5

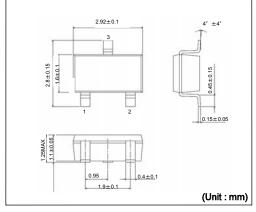


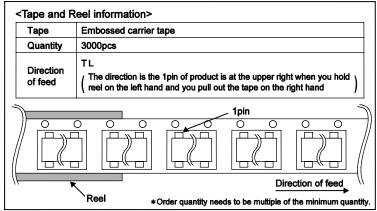


#### **VSOF5**



#### SSOP3





#### **●**Lineup

Marking	Detection	Part	Marking	Detection	Part	Marking	Detection	Part	Marking	Detection	Part
Iviaikiiig	Voltage	Number	Marking	Voltage	Number	Marking	Voltage	Number	Marking	Voltage	Number
EW 6.0	<b>)</b> V	BD4860	EB	4.1V	BD4841	GW	6.0V	BD4960	GB	4.1V	BD4941
EV 5.9	V	BD4859	EA	4.0V	BD4840	GV	5.9V	BD4959	GA	4.0V	BD4940
EU 5.8	V	BD4858	DV	3.9V	BD4839	GU	5.8V	BD4958	FV	3.9V	BD4939
ET 5.7	V	BD4857	DU	3.8V	BD4838	GT	5.7V	BD4957	FU	3.8V	BD4938
ES 5.6	V	BD4856	DT	3.7V	BD4837	GS	5.6V	BD4956	FT	3.7V	BD4937
ER 5.5	V	BD4855	DS	3.6V	BD4836	GR	5.5V	BD4955	FS	3.6V	BD4936
EQ 5.4	V	BD4854	DR	3.5V	BD4835	GQ	5.4V	BD4954	FR	3.5V	BD4935
EP 5.3	V	BD4853	DQ	3.4V	BD4834	GP	5.3V	BD4953	FQ	3.4V	BD4934
EN 5.2	V	BD4852	DP	3.3V	BD4833	GN	5.2V	BD4952	FP	3.3V	BD4933
EM 5.1	V	BD4851	DN	3.2V	BD4832	GM	5.1V	BD4951	FN	3.2V	BD4932
EL 5.0	V	BD4850	DM	3.1V	BD4831	GL	5.0V	BD4950	FM	3.1V	BD4931
EK 4.9	V	BD4849	DL	3.0V	BD4830	GK	4.9V	BD4949	FL	3.0V	BD4930
EJ 4.8	V	BD4848	DK	2.9V	BD4829	GJ	4.8V	BD4948	FK	2.9V	BD4929
EH 4.7	V	BD4847	DJ	2.8V	BD4828	GH	4.7V	BD4947	FJ	2.8V	BD4928
EG 4.6	V	BD4846	DH	2.7V	BD4827	GG	4.6V	BD4946	FH	2.7V	BD4927
EF 4.5	V	BD4845	DG	2.6V	BD4826	GF	4.5V	BD4945	FG	2.6V	BD4926
EE 4.4	V	BD4844	DF	2.5V	BD4825	GE	4.4V	BD4944	FF	2.5V	BD4925
ED 4.3	V	BD4843	DE	2.4V	BD4824	GD	4.3V	BD4943	FE	2.4V	BD4924
EC 4.2	V	BD4842	DD	2.3V	BD4823	GC	4.2V	BD4942	FD	2.3V	BD4923

Marking	Detection Voltage	Part Number									
Cm	6.0V	BD48E60	Ве	4.1V	BD48E41	Ff	6.0V	BD49E60	Ea	4.1V	BD49E41
Ck	5.9V	BD48E59	Bd	4.0V	BD48E40	Fe	5.9V	BD49E59	Dy	4.0V	BD49E40
Ch	5.8V	BD48E58	Вс	3.9V	BD48E39	Fd	5.8V	BD49E58	Dr	3.9V	BD49E39
Cg	5.7V	BD48E57	Bb	3.8V	BD48E38	Fc	5.7V	BD49E57	Dp	3.8V	BD49E38
Cf	5.6V	BD48E56	Ва	3.7V	BD48E37	Fb	5.6V	BD49E56	Dn	3.7V	BD49E37
Ce	5.5V	BD48E55	Ау	3.6V	BD48E36	Fa	5.5V	BD49E55	Dm	3.6V	BD49E36
Cd	5.4V	BD48E54	Ar	3.5V	BD48E35	Ey	5.4V	BD49E54	Dk	3.5V	BD49E35
Сс	5.3V	BD48E53	Ap	3.4V	BD48E34	Er	5.3V	BD49E53	Dh	3.4V	BD49E34
Cb	5.2V	BD48E52	An	3.3V	BD48E33	Ep	5.2V	BD49E52	Dg	3.3V	BD49E33
Ca	5.1V	BD48E51	Am	3.2V	BD48E32	En	5.1V	BD49E51	Df	3.2V	BD49E32
Ву	5.0V	BD48E50	Ak	3.1V	BD48E31	Em	5.0V	BD49E50	De	3.1V	BD49E31
Br	4.9V	BD48E49	Ah	3.0V	BD48E30	Ek	4.9V	BD49E49	Dd	3.0V	BD49E30
Вр	4.8V	BD48E48	Ag	2.9V	BD48E29	Eh	4.8V	BD49E48	Dc	2.9V	BD49E29
Bn	4.7V	BD48E47	Af	2.8V	BD48E28	Eg	4.7V	BD49E47	Db	2.8V	BD49E28
Bm	4.6V	BD48E46	Ae	2.7V	BD48E27	Ef	4.6V	BD49E46	Da	2.7V	BD49E27
Bk	4.5V	BD48E45	Ad	2.6V	BD48E26	Ee	4.5V	BD49E45	Су	2.6V	BD49E26
Bh	4.4V	BD48E44	Ac	2.5V	BD48E25	Ed	4.4V	BD49E44	Cr	2.5V	BD49E25
Bg	4.3V	BD48E43	Ab	2.4V	BD48E24	Ec	4.3V	BD49E43	Ср	2.4V	BD49E24
Bf	4.2V BD	48E42	Aa	2.3V	BD48E23	Eb	4.2V	BD49E42	Cn	2.3V	BD49E23

Marking	Detection Voltage	Part Number	Marking	Detection Voltage	Part Number	Marking	Detection Voltage	Part Number	Marking	Detection Voltage	Part Number
Cm	6.0V BD	48K60	Ве	4.1V BD	48K41	Ff	6.0V BD	49K60	Ea	4.1V	BD49K41
Ck	5.9V BD	48K59	Bd	4.0V BD	48K40	Fe	5.9V BD	49K59	Dy	4.0V	BD49K40
Ch	5.8V BD	48K58	Вс	3.9V BD	48K39	Fd	5.8V BD	49K58	Dr	3.9V	BD49K39
Cg	5.7V BD	48K57	Bb	3.8V BD	48K38	Fc	5.7V BD	49K57	Dp	3.8V	BD49K38
Cf	5.6V BD	48K56	Ва	3.7V BD	48K37	Fb	5.6V BD	49K56	Dn	3.7V	BD49K37
Ce	5.5V BD	48K55	Ay	3.6V BD	48K36	Fa	5.5V BD	49K55	Dm	3.6V	BD49K36
Cd	5.4V BD	48K54	Ar	3.5V BD	48K35	Ey	5.4V BD	49K54	Dk	3.5V	BD49K35
Сс	5.3V BD	48K53	Ap	3.4V BD	48K34	Er	5.3V BD	49K53	Dh	3.4V	BD49K34
Cb	5.2V BD	48K52	An	3.3V BD	48K33	Ep	5.2V BD	49K52	Dg	3.3V	BD49K33
Ca	5.1V BD	48K51	Am	3.2V BD	48K32	En	5.1V BD	49K51	Df	3.2V	BD49K32
Ву	5.0V BD	48K50	Ak	3.1V BD	48K31	Em	5.0V BD	49K50	De	3.1V	BD49K31
Br	4.9V BD	48K49	Ah	3.0V BD	48K30	Ek	4.9V BD	49K49	Dd	3.0V	BD49K30
Вр	4.8V BD	48K48	Ag	2.9V BD	48K29	Eh	4.8V BD	49K48	Dc	2.9V	BD49K29
Bn	4.7V BD	48K47	Af	2.8V BD	48K28	Eg	4.7V BD	49K47	Db	2.8V	BD49K28
Bm	4.6V BD	48K46	Ae	2.7V BD	48K27	Ef	4.6V BD	49K46	Da	2.7V	BD49K27
Bk	4.5V BD	48K45	Ad	2.6V BD	48K26	Ee	4.5V BD	49K45	Су	2.6V	BD49K26
Bh	4.4V BD	48K44	Ac	2.5V BD	48K25	Ed	4.4V BD	49K44	Cr	2.5V	BD49K25
Bg	4.3V BD	48K43	Ab	2.4V BD	48K24	Ec	4.3V BD	49K43	Ср	2.4V	BD49K24
Bf	4.2V BD	48K42	Aa	2.3V BD	48K23	Eb	4.2V BD	49K42	Cn	2.3V	BD49K23

Marking	Detection Voltage	Part Number	Marking	Detection Voltage	Part Number	Marking	Detection Voltage	Part Number	Marking	Detection Voltage	Part Number
Kb	6.0V BD	48L60	Gn	4.1V BD	48L41	Np	6.0V BD		Mg	4.1V	BD49L41
Ka	5.9V BD		Gm	4.0V BD		Nn	5.9V BD		Mf	4.0V	BD49L40
Ну	5.8V BD	48L58	Gk	3.9V BD	48L39	Nm	5.8V BD	49L58	Me	3.9V	BD49L39
Hr	5.7V BD	48L57	Gh	3.8V BD	48L38	Nk	5.7V BD	49L57	Md	3.8V	BD49L38
Нр	5.6V BD	48L56	Gg	3.7V BD	48L37	Nh	5.6V BD	49L56	Мс	3.7V	BD49L37
Hn	5.5V BD	48L55	Gf	3.6V BD	48L36	Ng	5.5V BD	49L55	Mb	3.6V	BD49L36
Hm	5.4V BD	48L54	Ge	3.5V BD	48L35	Nf	5.4V BD	49L54	Ma	3.5V	BD49L35
Hk	5.3V BD	48L53	Gd	3.4V BD	48L34	Ne	5.3V BD	49L53	Ky	3.4V	BD49L34
Hh	5.2V BD	48L52	Gc	3.3V BD	48L33	Nd	5.2V BD	49L52	Kr	3.3V	BD49L33
Hg	5.1V BD	48L51	Gb	3.2V BD	48L32	Nc	5.1V BD	49L51	Kp	3.2V	BD49L32
Hf	5.0V BD	48L50	Ga	3.1V BD	48L31	Nb	5.0V BD	49L50	Kn	3.1V	BD49L31
He	4.9V BD	48L49	Fy	3.0V BD	48L30	Na	4.9V BD	49L49	Km	3.0V	BD49L30
Hd	4.8V BD	48L48	Fr	2.9V BD	48L29	My	4.8V BD	49L48	Kk	2.9V	BD49L29
Hc	4.7V BD	48L47	Fp	2.8V BD	48L28	Mr	4.7V BD	49L47	Kh	2.8V	BD49L28
Hb	4.6V BD	48L46	Fn	2.7V BD	48L27	Мр	4.6V BD	49L46	Kg	2.7V	BD49L27
На	4.5V BD	48L45	Fm	2.6V BD	48L26	Mn	4.5V BD	49L45	Kf	2.6V	BD49L26
Gy	4.4V BD	48L44	Fk	2.5V BD	48L25	Mm	4.4V BD	49L44	Ke	2.5V	BD49L25
Gr	4.3V BD	48L43	Fh	2.4V BD	48L24	Mk	4.3V BD	49L43	Kd	2.4V	BD49L24
Gp	4.2V BD	48L42	Fg	2.3V BD	48L23	Mh	4.2V BD	49L42	Kc	2.3V	BD49L23

● Absolute Maximum Ratings (Ta=25°C)

F	Parameter S	ymbol	Limits	Unit	
Power Supply Volta	age	$V_{DD}$ -GND	-0.3 to +10	V	
Output Valtage	Nch Open Drain Output	V	GND-0.3 to +10	V	
Output Voltage	CMOS Output	V <sub>OUT</sub>	GND-0.3 to V <sub>DD</sub> +0.3	V	
Power		540		100	
Dissipation VSOF5 *2*3		Pd	210	mW	
Operating Tempera	ature	Topr	-40 to +105	°C	
Ambient Storage Te	emperature	Tstg	-55 to +125	°C	

<sup>\*1</sup> Use above Ta=25°C results in a 5.4mW loss per degree.

● Electrical Characteristics (Unless Otherwise Specified Ta=-40 to 105°C)

• Electrical Characteristics	s (Ullicaa i	Otherwise Specified	1a=-40 to 103 C)				ı
Parameter S	ymbol	Cor	ndition		Limit		Unit
Farailletei S	ymboi	Col	lullon	Min. T	yp.	Max.	Offic
Detection Voltage	V <sub>DET</sub> R	L=470kΩ, VDD=H→		V <sub>DET</sub> (T) ×0.99	V <sub>DET</sub> (T)	V <sub>DET</sub> (T) ×1.01	V
Output Delay Time "L→H" t	PLH	CL=100pF R L=100k	Ω *2			100	μs
Cutput Belay Time E 711 t	FLII	Vout=GND→50%				100	μο
			V <sub>DET</sub> =2.3-3.1V -		0.51	1.53	
Circuit Current when ON	Icc1 V	DD=V <sub>DET</sub> -0.2V *1	V <sub>DET</sub> =3.2-4.2V -		0.56	1.68	μA
Circuit Guirent when ON	ICCT V	DD-VDET-0.2V	V <sub>DET</sub> =4.3-5.2V -		0.60	1.80	μΑ
			V <sub>DET</sub> =5.3-6.0V -		0.66	1.98	
			V <sub>DET</sub> =2.3-3.1V -		0.75	2.25	
Circuit Current when OFF	Icc2 V	DD=V <sub>DET</sub> +2.0V *1	V <sub>DET</sub> =3.2-4.2V -		0.80	2.40	μA
Circuit Current when OFF			V <sub>DET</sub> =4.3-5.2V -		0.85	2.55	
			V <sub>DET</sub> =5.3-6.0V -		0.90	2.70	
Operating Voltage Dange	Vopl	VoL≤0.4V, Ta=25 to 1	105°C, RL=470kΩ 0.95		-	-	V
Operating Voltage Range	VOPL	VoL≤0.4V, Ta=-40 to	25°C, RL=470kΩ 1.20		-	-	V
(Lave) Overhaust Commont (Nach)	lo	VDS=0.5V, VDD=1.5V	, V <sub>DET</sub> =2.3-6.0V 0.4		1.0	-	A
'Low'Output Current (Nch)	lol	VDS=0.5V, VDD=2.4V	, V <sub>DET</sub> =2.7-6.0V 2.0		4.0	-	mA
(I limbio de la Compani (Dala)		VDS=0.5V, VDD=4.8V	, V <sub>DET</sub> =2.3-4.2V	0.7	1.4	-	
'High'Output Current (Pch)	Іон	VDS=0.5V, VDD=6.0V	, V <sub>DET</sub> =4.3-5.2V	0.9	1.8	-	mA
(BD49xxx Series)		VDS=0.5V, VDD=8.0V	, V <sub>DET</sub> =5.3-6.0V	1.1	2.2	-	
Leak Current when OFF	I <sub>leak</sub> V	DD=VDS=10V	*1			0.1	μA
(BD48xxx Series)	ileak *	22 120 101					μ, ,
Detection Voltage	V <sub>DET</sub> /ΔT	Ta=-40°C to 105°C		- ±10	0	±360	ppm/°C
Temperature coefficient	*DEI/AI	(Designed Guarante	e)	-10	•	±000	PP.1." 0
Hysteresis Voltage Voca(T): Standard Detect	ΔV <sub>DET</sub> V			DET×0.03	V DET×0.05	V DET×0.08	V

<sup>\*2</sup> Use above Ta=25°C results in a 2.1mW loss per degree.

<sup>\*3</sup> When a ROHM standard circuit board (70mm×70mm×1.6mm glass epoxy board) is mounted.

V<sub>DET</sub>(T): Standard Detection Voltage(2.3V to 6.0V, 0.1V step)
R<sub>L</sub>: Pull-up resistor to be connected between V<sub>OUT</sub> and power supply.
C<sub>L</sub>: Capacitor to be connected between V<sub>OUT</sub> and GND.

Designed Guarantee. (Outgoing inspection is not done on all products.) \*1 Guar antee is Ta=25°C.

<sup>\*2</sup>  $\text{tPLH:VDD=}(V_{DET} \text{ typ.-0.5V}) \rightarrow (V_{DET} \text{ typ.+0.5V})$ 

#### ●Block Diagrams

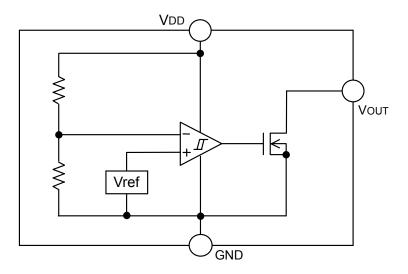


Fig.1 BD48xxx series

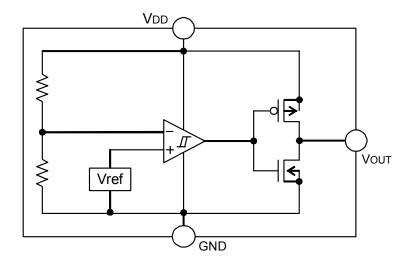


Fig.2 BD49xxx series

#### **●**Typical Performance Curves

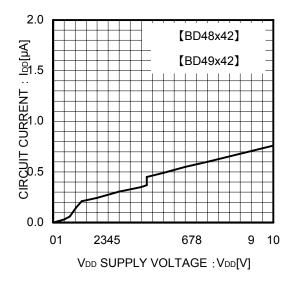


Fig.3 Circuit Current

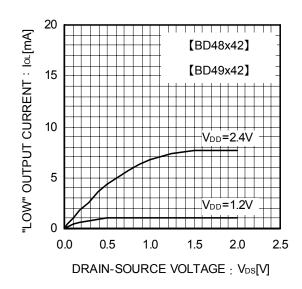


Fig.4 "Low" Output Current

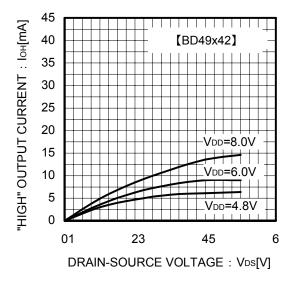


Fig.5 "High" Output Current

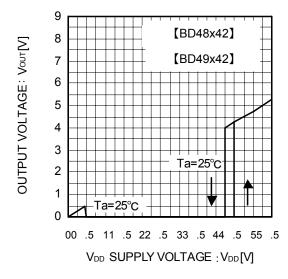
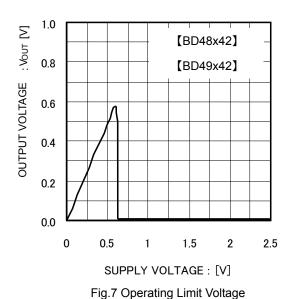
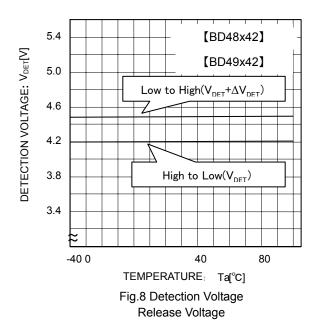
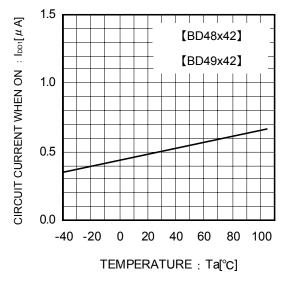
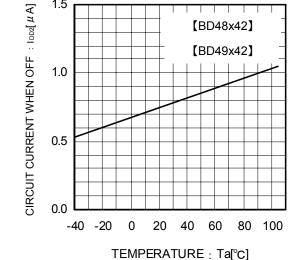


Fig.6 I/O Characteristics









1.5

Fig.9 Circuit Current when ON

Fig.10 Circuit Current when OFF

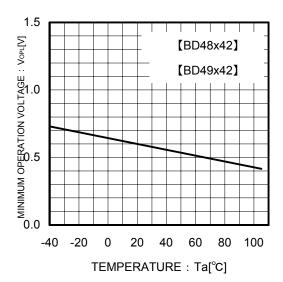


Fig.11 Operating Limit Voltage

#### Application Information

#### **Explanation of Operation**

For both the open dra in type (Fig.12) and the CMOS out put type (Fig.13), the detection and release voltages are used as threshold voltages. When the voltage applied to the  $V_{DD}$  pins reach es the applicable threshold voltage, the  $V_{OUT}$  terminal voltages witches from either "High" to "Low" or from "Low" to "High". Please refer to the Timing Waveform and Electrical Characteristics for information on hysteresis.

Because the BD48xxx series uses an open drain output type, it is possible to connect a pull-up resistor to  $V_{DD}$  or another power supply [The output "High" voltage ( $V_{OUT}$ ) in this case becomes  $V_{DD}$  or the voltage of the other power supply].

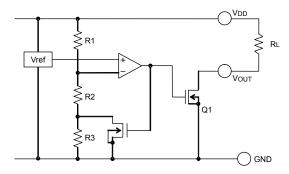


Fig.12 (BD48xxx series Internal Block Diagram)

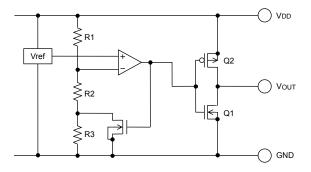


Fig.13 (BD49xxx series Internal Block Diagram)

#### **Reference Data**

Examples of Leading (t<sub>PLH</sub>) and Falling (t<sub>PHL</sub>) Output

Part Number	t <sub>PLH</sub> (µs) t	PHL (µS)
BD48x45	39.5	87.8
BD49x45	32.4	52.4

 $V_{DD}$ =4.3V $\rightarrow$ 5.1V  $V_{DD}$ =5.1V $\rightarrow$ 4.3V

The figures will vary with the application, so please confirm actual operating conditions before use.

#### **Timing Waveform**

Example: the following shows the relationship between the input voltages  $V_{DD}$  and the output voltage  $V_{OUT}$  when the input power supply voltage  $V_{DD}$  is made to sweep up and sweep down (the circuits are those in Fig.12 and 13).

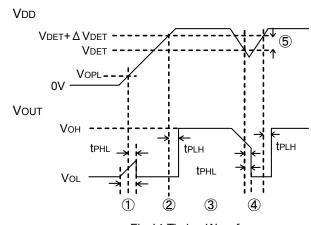


Fig.14 Timing Waveform

- ① When the power supply is turned on, the output is unsettled from after over the operating limit voltage ( $V_{OPL}$ ) until  $t_{PHL}$ . Therefore it is possible that the reset signal is not valid when the rise time of  $V_{DD}$  is faster than  $t_{PHL}$ .
- When  $V_{DD}$  is greater than  $V_{OPL}$  but less than the reset release voltage ( $V_{DET} + \Delta V_{DET}$ ), the output voltages will switch to Low.
- (3) If  $V_{DD}$  exce eds the reset releas e voltage ( $V_{DET} + \Delta V_{DET}$ ), then  $V_{OUT}$  switches from L to H.
- $^{(4)}$  If  $V_{DD}$  drops below the detection voltage ( $V_{DET}$ ) when the power supply is powered down or when there is a power supply fluctuation,  $V_{OUT}$  switches to L (with a delay of  $t_{PHL}$ ).
- $^{(5)}$  The potential difference between the detection voltage and the release volt age is kno wn a s t he h ysteresis width (  $\Delta V_{\text{DET}}$ ). The system is designed such that the output does not flip-flop with power supply fluctuations within this hysteresis width, preventing malfunctions due to noise.

<sup>\*</sup>This data is for reference only.

#### Circuit Applications

Examples of a common power supply detection reset circuit.

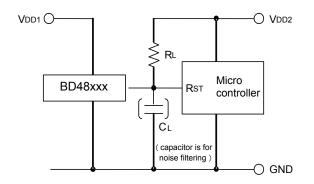


Fig.15 Open Drain Output Type

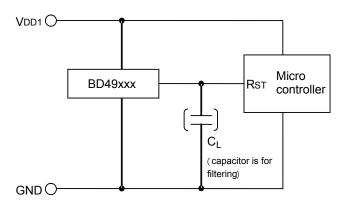


Fig.16 CMOS Output Type

Application e xamples of BD48 xxx seri es (Open Drai n output type) and BD49xxx series (CMOS output type) are shown below.

CASE1: the po wer supply of the microcontroller (V  $_{DD2}$ ) differs from the power supply of the reset detection (V $_{DD1}$ ). Use a n o pen drain out put t ype (BD 48xxx) device with a load resistance R $_{L}$  attached as shown in figure 15.

CASE2: the power supply of the microc ontroller ( $V_{DD1}$ ) is same as the power supply of the reset detection ( $V_{DD1}$ ). Use a CMOS output type (B D49xxx) d evice or a n op en drain device with a pul I up r esistor bet ween out put a nd VDD1.

When a ca pacitance  $C_L$  for noise filtering is connected to the V  $_{OUT}$  pin (t he reset signa I inp ut t erminal of t he microcontroller), please take into account the waveform of the rise and fall of the output voltage ( $V_{OUT}$ ).

The Electrical characteristics were measured using  $R_L \text{= } 470 k\Omega$  and  $C_L \text{= } 100 pF.$ 

#### Operational Notes

#### 1 . Absolute maximum range

Absolute Maximum Ratings are those values beyond which the life of a device may be destroyed. We cannot be defined the failure mode, such as short mode or open mode. Therefore a physical security countermeasure, like fuse, is to be given when a specific mode to be beyond absolute maximum ratings is considered.

#### 2 . GND potential

GND terminal should be a lowest voltage potential every state.

Please make sure all pins, which are over ground even if, include transient feature.

#### 3 . Electrical Characteristics

Be sure to check the electrical characteristics that are one the tentative specification will be changed by temperature, supply voltage, and external circuit.

#### 4 . Bypass Capacitor for Noise Rejection

Please put into the capacitor of  $1\mu\text{F}$  or more between  $V_{DD}$  pin and GND, and the capacitor of about 1000pF between  $V_{OUT}$  pin and GND, to reject noise. If extremely big capacitor is used, transient response might be late. Please confirm sufficiently for the point.

#### 5 . Short Circuit between Terminal and Soldering

Don't short-circuit between Output pin and  $V_{DD}$  pin, Output pin and GND pin, or  $V_{DD}$  pin and GND pin. When soldering the IC on circuit bo ard, pleas e be unus ually cautious about the orientation and the position of the IC. When the orientation is mistaken the IC may be destroyed.

#### 6 . Electromagnetic Field

Mal-function may happen when the device is used in the strong electromagnetic field.

- 7. The  $V_{DD}$  line inpedance might cause oscillation because of the detection current.
- 8. A V<sub>DD</sub> -GND capacitor (as close connection as possible) should be used in high V<sub>DD</sub> line impedance condition.
- 9 . Lower than the mininum input voltage makes the VouT high impedance, and it must be VDD in pull up (VDD) condition.
- 10. This IC has extremely high impedance terminals. Small leak current due to the uncleanness of PCB surface might cause unexpected o perations. Appli cation values in these conditions should be selected carefully. If the leakage is assumed between the V<sub>OUT</sub> terminal and the GND terminal, the pull-up resistor should be less than 1/10 of the assumed leak age resistance.

#### 11. External parameters

The recommended parameter range for  $R_L$  is  $10k\Omega$  to  $1M\Omega$ . There are many factors (board layout, etc) that can affect characteristics. Please verify and confirm using practical applications.

#### 12. Power on reset operation

Please note that the power on reset output varies with the V<sub>DD</sub> rise up time. Please verify the actual operation.

#### 13. Precautions for board inspection

Connecting low-impedance capacitors to run inspections with the board may produce stress on the IC. Therefore, be certain to use proper discharge procedure before each process of the test operation.

To prevent el ectrostatic acc umulation a nd dischar ge in t he assembl y proc ess, t horoughly gr ound yourself a nd an y equipment that could sustain ESD damage, and continue observing ESD-prevention procedures in all handing, transfer and storage operations. Before attempting to connect components to the test setup, make certain that the power supply is OFF. Likewise, be sure the power supply is OFF before removing any component connected to the test setup.

14. When the power supply, is turned on be cause of in certain cases, momentary Rash-current flow into the IC at the logic unsettled, the couple capacitance, GND pattern of width and leading line must be considered.

#### Status of this document

The Japanese version of this document is formal specification. A customer may use this translation version only for a reference to help reading the formal version.

If there are any differences in translation version of this document formal version takes priority.

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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in pla ces where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - If Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or W ashing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4) The Products are not subject to radiation-proof design.
- 5) Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6) In particular, if a transient load (a large am ount of load a pplied in a sho rt period of time, such as pulse) is applie d, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7) De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8) Confirm that operation temperature is within the specified range described in the product specification.
- 9) ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1) When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2) In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

- Precautions Regarding Application Examples and External Circuits
  - If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Prod ucts and external components, including transient characteristics, as well as static characteristics.
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#### Precaution for Electrostatic

This Product is electrostatic sensitive pro duct, which may be damaged due to electrostatic discharg e. Please take pro per caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### Precaution for Storage / Transportation

- 1) Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2) Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is stron gly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3) Store / transport cartons in the correct direction, which is in dicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4) Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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